

Electron-Beam Evaporation System #2 (PVD-75)

Overview

Six-pocket electron beam evaporation system with computer-controlled, automated deposition. Deposition materials are restricted to approved metals only.

LMACS Name	Electron-Beam Evaporation System #2 (PVD-75)
Confluence Label	pvd-75
Process Area	DEPOSITION
Location	10k aisle 1
Model	PVD-75
Vendor	Kurt J Lesker
Team	Timothy Harrison Glenn Elashuk Aaron Hryciw

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System Features

	6-pocket e-beam hearth: Al, Ti, Cr, Au, Ag, and Ni. Pocket 5 material (Ag), may be changed out at user request
	Alternative approved materials (available with >24 hr notice): Ag, Cu
	Cryo pumped with a base pressure of <1e-7 Torr; <4e-7 Torr achievable within 30 min pumpdown
	Automatic deposition recipes
	300 mm Ø platen with room for substrates up to 150 mm diameter
	Rotating substrate holder
	Typical uniformity of <5% over a 150 mm wafer, <2% over a 100 mm wafer

Documents

Operating Procedure	PVD-75 Evaporation System SOP
Hazard Assessment	Electron-Beam Evaporation System #2 (PVD-75) HA
QCM Material Parameters	QCM Material Parameters
Pocket 5 Material Change	How-To Request an Alternative Approved PVD-75 Material

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